

L Number	Hits	Search Text	DB	Time stamp
3	37	((wafer or semiconductor) and (pedestal same vertical\$4) and (mult\$4 near5 chamber\$2)) and deposition) and chuck and heater	USPAT; US-PGPUB	2003/11/18 10:02
4	25	5909994.URPN.	USPAT	2003/11/18 09:55
5	58	(wafer or semiconductor) and vertical and multichamber and deposition and chuck and heater	USPAT; US-PGPUB	2003/11/18 10:03
6	66	(wafer or semiconductor) and vertical and multichamber and deposition and chuck	USPAT; US-PGPUB	2003/11/18 10:03
7	201	(wafer or semiconductor) and vertical and multichamber and deposition	USPAT; US-PGPUB	2003/11/18 10:03
8	172	((wafer or semiconductor) and vertical and multichamber and deposition) and (pedestal or support)	USPAT; US-PGPUB	2003/11/18 10:04
9	11	((wafer or semiconductor) and vertical and multichamber and deposition) and (pedestal or support)) and 700/\$.ccls.	USPAT; US-PGPUB	2003/11/18 10:05
12	2	6178660.URPN.	USPAT	2003/11/18 10:12
13	13	("4795299"   "4917556"   "5228206"   "5423971"   "5529657"   "5611861"   "5755938"   "5759334"   "5855675"   "5863170"   "5880924"   "5882165"   "5886864").PN.	USPAT	2003/11/18 10:13
14	1	4423701.pn.	USPAT; US-PGPUB	2003/11/18 10:23
15	1	4423701.pn. and vertical	USPAT; US-PGPUB	2003/11/18 10:23
16	15	(US-4423701-\$ or US-5292554-\$ or US-5518542-\$ or US-4664939-\$ or US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-6143086-\$ or US-6497767-\$ or US-6178660-\$ or US-5772773-\$ or US-6318945-\$).did. or (US-20020056414-\$ or US-20020197863-\$ or US-20020076490-\$).did.	USPAT; US-PGPUB	2003/11/18 10:40
17	51	multizone and deposition and wafer	USPAT; US-PGPUB	2003/11/18 10:45
18	25	(multizone and deposition and wafer) and vertical	USPAT; US-PGPUB	2003/11/18 10:40
19	4	((multizone and deposition and wafer) and vertical) and pedestal	USPAT; US-PGPUB	2003/11/18 10:42
20	1	6352593.pn.	USPAT; US-PGPUB	2003/11/18 10:42
21	220	(multizone or multi-zone) and deposition and wafer	USPAT; US-PGPUB	2003/11/18 10:46
22	0	((multizone or multi-zone) and deposition and wafer) and verticle	USPAT; US-PGPUB	2003/11/18 10:46
23	126	((multizone or multi-zone) and deposition and wafer) and vertical	USPAT; US-PGPUB	2003/11/18 10:46
24	104	((multizone or multi-zone) and deposition and wafer) and vertical) and (support or pedestal)	USPAT; US-PGPUB	2003/11/18 10:46
25	63	((((multizone or multi-zone) and deposition and wafer) and vertical) and (support or pedestal)) and heater	USPAT; US-PGPUB	2003/11/18 10:46
26	27	(((((multizone or multi-zone) and deposition and wafer) and vertical) and (support or pedestal)) and heater) and chuck	USPAT; US-PGPUB	2003/11/18 11:12
27	2	6413321.URPN.	USPAT	2003/11/18 10:50
28	17	("3627590"   "4798165"   "5045346"   "5221414"   "5230741"   "5238499"   "5244730"   "5350427"   "5366585"   "5374594"   "5447570"   "5589233"   "5614055"   "5855681"   "5871811"   "5879128"   "6020035").PN.	USPAT	2003/11/18 10:50
29	1329	118/719.ccls.	USPAT; US-PGPUB	2003/11/18 11:12

30	73	118/719.ccls. and pedestal and vertical	USPAT; US-PGPUB	2003/11/18 12:47
31	450	118/719.ccls. and (pedestal or support) and vertical	USPAT; US-PGPUB	2003/11/18 11:13
32	25	(118/719.ccls. and pedestal and vertical) and zone and gas	USPAT; US-PGPUB	2003/11/18 12:55
33	253	118/719.ccls. and aperture	USPAT; US-PGPUB	2003/11/18 12:55
34	171	(118/719.ccls. and aperture) and vertical\$3	USPAT; US-PGPUB	2003/11/18 12:55
35	112	((118/719.ccls. and aperture) and vertical\$3) and wafer	USPAT; US-PGPUB	2003/11/18 12:55
36	56	((118/719.ccls. and aperture) and vertical\$3) and wafer) and (region or zone)	USPAT; US-PGPUB	2003/11/18 12:57
37	3	((118/719.ccls. and aperture) and vertical\$3) and wafer) and (region or zone)) and piston	USPAT; US-PGPUB	2003/11/18 13:26
38	30	4430149.URPN.	USPAT	2003/11/18 13:13
39	823	700/121.ccls.	USPAT; US-PGPUB	2003/11/18 13:27
40	257	700/121.ccls. and deposition and wafer	USPAT; US-PGPUB	2003/11/18 13:27
41	11	(700/121.ccls. and deposition and wafer) and zone and aperture	USPAT; US-PGPUB	2003/11/18 13:27
42	44138	438/\$.ccls. and deposition	USPAT; US-PGPUB	2003/11/18 13:30
43	12	(438/\$.ccls. and deposition) and pedestal and piston	USPAT; US-PGPUB	2003/11/18 13:34
44	607	438/680.ccls.	USPAT; US-PGPUB	2003/11/18 13:36
45	10	deposition and wafer adj support and (multizone or multi-zone) and aperture and vertical\$4 and heat\$4	USPAT; US-PGPUB	2003/11/18 13:39
46	4	cvd and pedestal same piston	USPAT; US-PGPUB	2003/11/18 13:48
47	17	("4382739"   "4513855"   "4590380"   "4619573"   "4632624"   "4746256"   "4801241"   "4861222"   "4872947"   "4894132"   "4902531"   "4915564"   "4923584"   "5051054"   "5098198"   "5108570"   "5131460").PN.	USPAT	2003/11/18 13:40
48	607	438/680.ccls.	USPAT; US-PGPUB	2003/11/18 13:48
49	26	438/680.ccls. and wafer adj support	USPAT; US-PGPUB	2003/11/18 14:04
50	25	438/680.ccls. and vertical and pedestal	USPAT; US-PGPUB	2003/11/18 14:04
51	19	(438/680.ccls. and vertical and pedestal) not (438/680.ccls. and wafer adj support)	USPAT; US-PGPUB	2003/11/18 14:09
52	8	("4951601"   "5246881"   "5366585"   "5516367"   "5558717"   "5846332"   "5853607"   "5885356").PN.	USPAT	2003/11/18 14:06
53	2	6063441.URPN.	USPAT	2003/11/18 14:08
54	323	438/478.ccls.	USPAT; US-PGPUB	2003/11/18 14:09
55	14	438/478.ccls. and pedestal	USPAT; US-PGPUB	2003/11/18 14:12
56	690	wafer and deposition and support same screw and vertical	USPAT; US-PGPUB	2003/11/18 14:12
57	245	(wafer and deposition and support same screw and vertical) and cvd	USPAT; US-PGPUB	2003/11/18 14:12
58	123	((wafer and deposition and support same screw and vertical) and cvd) and heater	USPAT; US-PGPUB	2003/11/18 14:13
59	47	((wafer and deposition and support same screw and vertical) and cvd) and heater) and zone	USPAT; US-PGPUB	2003/11/18 14:20
61	24	5620523.URPN.	USPAT	2003/11/18 14:20
60	38	deposition and wafer and ball adj screw and zone	USPAT; US-PGPUB	2003/11/18 14:31

62	275	cvd and ball adj screw	USPAT; US-PGPUB	2003/11/18 14:31
63	6	(cvd and ball adj screw) and zone and aperture	USPAT; US-PGPUB	2003/11/18 14:31
73	0	6497767.URPN.	USPAT	2003/11/18 15:14
74	10	("5273588"   "5418885"   "5446825"   "5688331"   "5796074"   "5855675"   "5916370"   "6001183"   "6190113"   "6190460").PN.	USPAT	2003/11/18 15:15
75	1	6497767.pn.	USPAT; US-PGPUB	2003/11/18 16:30
76	1	6650315.pn.	USPAT; US-PGPUB	2003/11/18 16:49
77	1	6650346.pn.	USPAT; US-PGPUB	2003/11/18 16:50
-	498	atomic adj layer adj deposition	USPAT; US-PGPUB	2003/07/28 11:14
-	194	(atomic adj layer adj deposition) and chamber and region\$1	USPAT; US-PGPUB	2003/02/27 15:50
-	94	((atomic adj layer adj deposition) and chamber and region\$1) and @ad<=20010727	USPAT; US-PGPUB	2003/02/27 16:43
-	67	((atomic adj layer adj deposition) and chamber and region\$1) and @ad<=20010727) and wafer	USPAT; US-PGPUB	2003/02/27 15:51
-	16	((((atomic adj layer adj deposition) and chamber and region\$1) and @ad<=20010727) and wafer) and support	USPAT; US-PGPUB	2003/02/27 15:51
-	12	(((((atomic adj layer adj deposition) and chamber and region\$1) and @ad<=20010727) and wafer) and support) and heater	USPAT; US-PGPUB	2003/02/27 16:01
-	1	5951776.pn.	USPAT; US-PGPUB	2003/02/27 16:06
-	1	6525747.pn.	USPAT; US-PGPUB	2003/02/27 16:40
-	1	"6174805".PN.	USPAT; US-PGPUB	2003/02/27 16:36
-	1	"6132514".PN.	USPAT; US-PGPUB	2003/02/27 16:36
-	1	"6071552".PN.	USPAT; US-PGPUB	2003/02/27 16:37
-	1	"5998871".PN.	USPAT; US-PGPUB	2003/02/27 16:37
-	1	"5998871".PN.	USPAT; US-PGPUB	2003/02/27 16:37
-	1	"5972785".PN.	USPAT; US-PGPUB	2003/02/27 16:37
-	1	"5916365".PN.	USPAT; US-PGPUB	2003/02/27 16:37
-	1	"5416045".PN.	USPAT; US-PGPUB	2003/02/27 16:38
-	1	"5344792".PN.	USPAT; US-PGPUB	2003/02/27 16:38
-	1	"6190732".PN.	USPAT; US-PGPUB	2003/02/27 16:39
-	1	"6174377".PN.	USPAT; US-PGPUB	2003/02/27 16:39
-	1	"5935338".PN.	USPAT; US-PGPUB	2003/02/27 16:40
-	1	"5879459".PN.	USPAT; US-PGPUB	2003/02/27 16:40
-	1	"5582866".PN.	USPAT; US-PGPUB	2003/02/27 16:40
-	655	700/121.ccls.	USPAT; US-PGPUB	2003/02/27 16:40
-	213	700/121.ccls. and deposition	USPAT; US-PGPUB	2003/02/27 16:41
-	113	(700/121.ccls. and deposition) and chamber	USPAT; US-PGPUB	2003/02/27 16:41
-	90	((700/121.ccls. and deposition) and chamber) and @ad<=20010727	USPAT; US-PGPUB	2003/03/03 14:47

-	3	((700/121.ccls. and deposition) and chamber) and @ad<=20010727) and piston	USPAT; US-PGPUB	2003/02/27 16:41
-	1	((atomic adj layer adj deposition) and chamber and region\$1) and @ad<=20010727) and piston	USPAT; US-PGPUB	2003/02/27 16:50
-	1228	118/719.ccls.	USPAT; US-PGPUB	2003/02/27 16:50
-	55	118/719.ccls. and wafer and piston	USPAT; US-PGPUB	2003/02/27 16:50
-	16	(118/719.ccls. and wafer and piston) and aperture	USPAT; US-PGPUB	2003/02/27 16:51
-	15	kosowski.xa.	USPAT; US-PGPUB	2003/03/03 14:05
-	4183	deposition and wafer and support and chamber and region\$2 and temperature and two and gas	USPAT; US-PGPUB	2003/03/03 14:47
-	3626	(deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<=20010727	USPAT; US-PGPUB	2003/03/03 17:34
-	167	((deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<=20010727) and piston	USPAT; US-PGPUB	2003/03/03 14:50
-	11	((deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<=20010727) and piston) and monolayer	USPAT; US-PGPUB	2003/03/03 14:51
-	90	((deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<=20010727) and atomic adj layer	USPAT; US-PGPUB	2003/03/03 14:51
-	1413684	((deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<=20010727) and atomic adj layer) and deposition near\$5 region\$1	USPAT; US-PGPUB	2003/03/03 14:53
-	90	((deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<=20010727) and atomic adj layer) and (deposition near\$5 region\$1)	USPAT; US-PGPUB	2003/03/03 16:18
-	1	"6174805".PN.	USPAT; US-PGPUB	2003/03/03 15:11
-	1	"6132514".PN.	USPAT; US-PGPUB	2003/03/03 15:11
-	1	"6071552".PN.	USPAT; US-PGPUB	2003/03/03 15:11
-	1	"5998871".PN.	USPAT; US-PGPUB	2003/03/03 15:11
-	4	((deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<=20010727) and moveable adj support	USPAT; US-PGPUB	2003/03/03 16:35
-	64	deposition and moveable adj support	USPAT; US-PGPUB	2003/03/03 16:35
-	62	(deposition and moveable adj support) and @ad<=20010727	USPAT; US-PGPUB	2003/03/03 16:37
-	25	((deposition and moveable adj support) and @ad<=20010727) and wafer	USPAT; US-PGPUB	2003/03/03 17:16
-	1	"5013400".PN.	USPAT; US-PGPUB	2003/03/03 16:45
-	1	"4990374".PN.	USPAT; US-PGPUB	2003/03/03 16:45
-	1	"4978412".PN.	USPAT; US-PGPUB	2003/03/03 16:46
-	1	"4963713".PN.	USPAT; US-PGPUB	2003/03/03 16:46
-	655	700/121.ccls.	USPAT; US-PGPUB	2003/03/03 17:16
-	2	700/121.ccls. and atomic adj layer adj deposition	USPAT; US-PGPUB	2003/03/03 17:33
-	21	interconnected with deposition with region\$2	USPAT; US-PGPUB	2003/03/03 17:33

-	21	(interconnected with deposition with region\$2) and @ad<=20010727	USPAT; US-PGPUB	2003/03/04 10:10
-	1	4423701.pn.	USPAT; US-PGPUB	2003/03/04 10:10
-	1	4423701.pn. and (heater or temperature)	USPAT; US-PGPUB	2003/03/04 11:13
-	9	(US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-5292554-\$ or US-4423701-\$ or US-4664939-\$).did. or (US-20020197863-\$ or US-20020076490-\$ or US-20020056414-\$).did.	USPAT; US-PGPUB	2003/03/04 13:26
-	2	((US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-5292554-\$ or US-4423701-\$ or US-4664939-\$).did. or (US-20020197863-\$ or US-20020076490-\$ or US-20020056414-\$).did.) and aperture	USPAT; US-PGPUB	2003/03/04 13:51
-	0	4423701.pn. and gase	USPAT; US-PGPUB	2003/03/04 13:51
-	1	4423701.pn. and gas	USPAT; US-PGPUB	2003/03/04 13:51
-	1	4664939.pn. and gas	USPAT; US-PGPUB	2003/03/04 14:09
-	2	((US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-5292554-\$ or US-4423701-\$ or US-4664939-\$).did. or (US-20020197863-\$ or US-20020076490-\$ or US-20020056414-\$).did.) and electrostatic	USPAT; US-PGPUB	2003/03/04 14:18
-	0	((US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-5292554-\$ or US-4423701-\$ or US-4664939-\$).did. or (US-20020197863-\$ or US-20020076490-\$ or US-20020056414-\$).did.) and piston	USPAT; US-PGPUB	2003/03/04 14:18
-	18	atomic adj layer adj deposition and piston	USPAT; US-PGPUB	2003/03/04 14:22
-	437	deposition and chamber and support and wafer and piston	USPAT; US-PGPUB	2003/03/04 14:23
-	242	(deposition and chamber and support and wafer and piston) and region and gas	USPAT; US-PGPUB	2003/03/04 14:23
-	191	((deposition and chamber and support and wafer and piston) and region and gas) and @ad<=20010727	USPAT; US-PGPUB	2003/03/04 14:25
-	94	deposition and wafer adj support and piston	USPAT; US-PGPUB	2003/03/04 14:25
-	83	(deposition and wafer adj support and piston) and @ad<=20010727	USPAT; US-PGPUB	2003/03/04 14:26
-	8	((deposition and wafer adj support and piston) and @ad<=20010727) and wafer adj support with piston	USPAT; US-PGPUB	2003/03/04 14:28
-	1	5228502.pn.	USPAT; US-PGPUB	2003/03/04 14:28
-	10	(US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-5292554-\$ or US-4664939-\$ or US-4423701-\$ or US-5518542-\$).did. or (US-20020076490-\$ or US-20020197863-\$ or US-20020056414-\$).did.	USPAT; US-PGPUB	2003/07/25 14:05
-	1	((US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-5292554-\$ or US-4664939-\$ or US-4423701-\$ or US-5518542-\$).did. or (US-20020076490-\$ or US-20020197863-\$ or US-20020056414-\$).did.) and elevation	USPAT; US-PGPUB	2003/07/25 14:06
-	8	((US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-5292554-\$ or US-4664939-\$ or US-4423701-\$ or US-5518542-\$).did. or (US-20020076490-\$ or US-20020197863-\$ or US-20020056414-\$).did.) and vertical	USPAT; US-PGPUB	2003/07/25 14:11
-	58	dworkin.in.	USPAT; US-PGPUB	2003/07/28 11:14
-	1	dworkin.in. and vendor	USPAT; US-PGPUB	2003/07/28 11:56

-	20721	image adj planes	USPAT; US-PGPUB	2003/07/28 11:56
-	1159	(image adj planes) and 345/\$.ccls.	USPAT; US-PGPUB	2003/07/28 11:56
-	680	118/729.ccls.	USPAT; US-PGPUB	2003/11/17 16:10
-	411	118/729.ccls. and (vertical or elevation)	USPAT; US-PGPUB	2003/11/17 16:10
-	306	((118/729.ccls. and (vertical or elevation)) and deposition	USPAT; US-PGPUB	2003/11/17 16:10
-	50	((118/729.ccls. and (vertical or elevation)) and deposition) and chuck	USPAT; US-PGPUB	2003/11/17 16:10
-	48	((118/729.ccls. and (vertical or elevation)) and deposition) and chuck) and (zone or chamber)	USPAT; US-PGPUB	2003/11/17 16:11
-	12	((118/729.ccls. and (vertical or elevation)) and deposition) and chuck) and (zone or chamber)) and pedestal	USPAT; US-PGPUB	2003/11/17 16:16
-	9	((118/729.ccls. and (vertical or elevation)) and deposition) and chuck) and (zone or chamber)) and pedestal) and ((118/729.ccls. and (vertical or elevation)) and deposition) and (pedestal same vertical\$3))	USPAT; US-PGPUB	2003/11/17 16:19
-	32	((118/729.ccls. and (vertical or elevation)) and deposition) and (pedestal same vertical\$3)	USPAT; US-PGPUB	2003/11/17 16:50
-	1	6143086.URPN.	USPAT	2003/11/17 16:27
-	16	("3306768"   "3641974"   "4724621"   "4938815"   "5065698"   "5094885"   "5135629"   "5169684"   "5192371"   "5213650"   "5228501"   "5238499"   "5304249"   "5474612"   "5589224"   "5803977").PN.	USPAT	2003/11/17 16:27
-	225	((wafer or semiconductor) and (pedestal same vertical\$4) and (mult\$4 near5 chamber\$2)	USPAT; US-PGPUB	2003/11/17 16:51
-	209	((wafer or semiconductor) and (pedestal same vertical\$4) and (mult\$4 near5 chamber\$2)) and deposition	USPAT; US-PGPUB	2003/11/17 16:51
-	16	5855675.URPN.	USPAT	2003/11/17 16:52